MA3S795EG

Silicon epitaxial planar type

For switching
For wave detection

■ Features

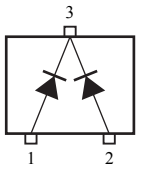
- High-density mounting is possible
- Forward voltage V_F , optimum for low voltage rectification: $V_F < 0.3$ V
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

■ Package

- Code
  SSMini3-F3
- Pin Name
  1: Anode 1
  2: Anode 2
  3: Cathode

■ Marking Symbol: M3D

■ Internal Connection



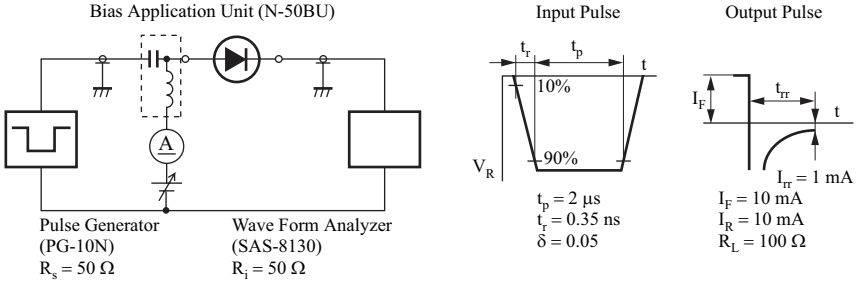
■ Absolute Maximum Ratings $T_a = 25°C$

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Maximum peak reverse voltage		V_{RM}	30	V
Forward current	Single	I_F	30	mA
	Double		20	
Peak forward current	Single	I_{FM}	150	mA
	Double		110	
Junction temperature		T_j	125	°C
Storage time		T_{stg}	–55 to +125	°C

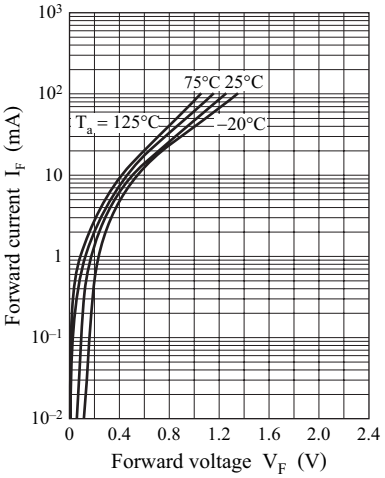
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 1 mA			0.3	V
	V_{F2}	I_F = 30 mA			1.0	
Reverse current	I_R	V_R = 30 V			30	μA
Terminal capacitance	C_t	V_R = 1 V, f = 1 MHz		1.5		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 10 mA, I_{rr} = 1 mA, R_L = 100 Ω		1.0		ns
Detection efficiency	η	$V_{IN} = 3\ V_{(peak)}$, f = 30 MHz R_L = 3.9 kΩ, C_L = 10 pF		65		%

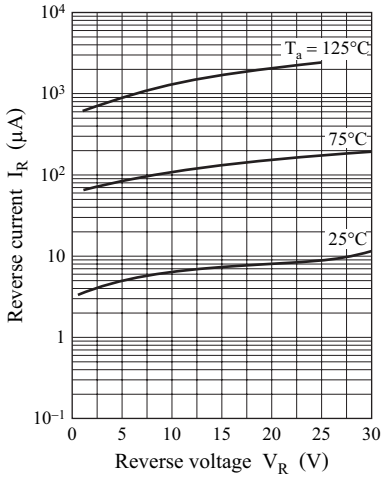
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz
4. *: t_{rr} measurement circuit



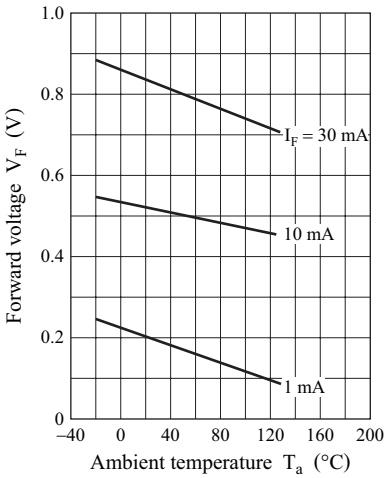
I_F — V_F



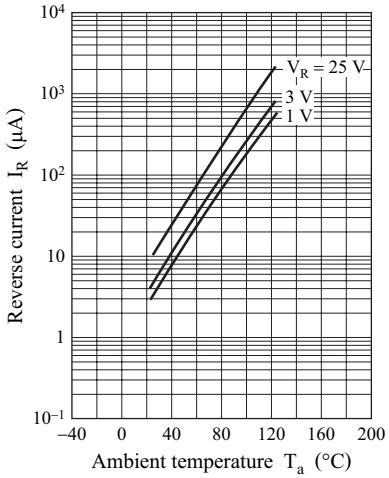
I_R — V_R



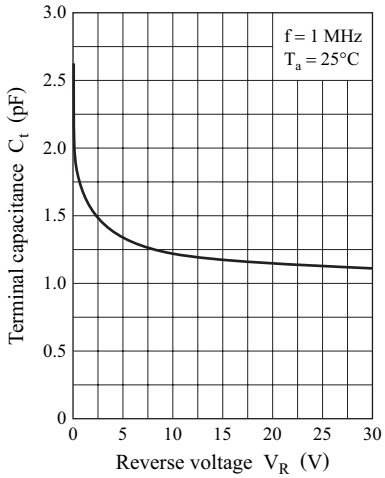
V_F — T_a



I_R — T_a

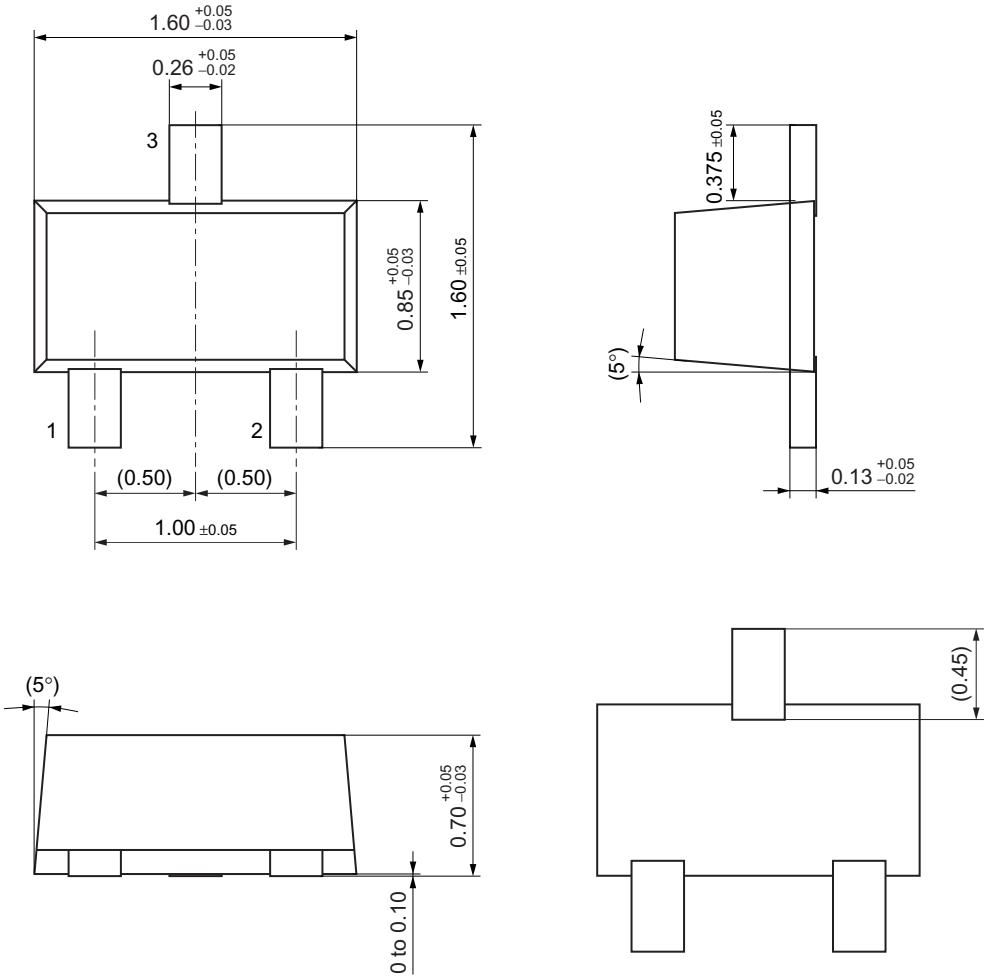


C_t — V_R



SSMini3-F3

Unit: mm



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